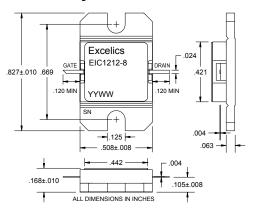


#### UPDATED 01/04/2006

# 12.20-12.70 GHz 8-Watt Internally Matched Power FET

### FEATURES

- 12.20- 12.70GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +39.0 dBm Output Power at 1dB Compression
- 6.5 dB Power Gain at 1dB Compression
- 27% Power Added Efficiency
- -46 dBc IM3 at PO = 28.5 dBm SCL
- Hermetic Metal Flange Package
- 100% Tested for DC, RF, and R<sub>TH</sub>



## ELECTRICAL CHARACTERISTICS ( $T_a = 25^{\circ}C$ )

#### Caution! ESD sensitive device.

**EIC1212-8** 

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SYMBOL	PARAMETERS/TEST CONDITIONS <sup>1</sup>	MIN	ТҮР	MAX	UNITS
$P_{1dB}$	Output Power at 1dB Compression $f = 12.20-12.70$ GHz $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200$ mA	38.5	39.0		dBm
G <sub>1dB</sub>	Gain at 1dB Compressionf = 12.20-12.70GHz $V_{DS}$ = 10 V, $I_{DSQ} \approx 2200$ mA	5.5	6.5		dB
∆G	$    Gain \ Flatness \qquad \qquad f = 12.20-12.70 \ GHz \\ V_{DS} = 10 \ V, \ I_{DSQ} \approx 2200 \ mA $			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200 \text{mA}$ f = 12.20-12.70GHz		27		%
Id <sub>1dB</sub>	Drain Current at 1dB Compression f = 12.20-12.70GHz		2300	2600	mA
IM3	Output 3rd Order Intermodulation Distortion $\Delta f = 10 \text{ MHz}$ 2-Tone Test; Pout = 28.5 dBm S.C.L <sup>2</sup> $V_{DS} = 10 \text{ V}$ , $I_{DSQ} \approx 65\%$ IDSS $f = 12.70 \text{GHz}$	-43	-46		dBc
I <sub>DSS</sub>	Saturated Drain Current $V_{DS}$ = 3 V, $V_{GS}$ = 0 V		4000	5000	mA
V <sub>P</sub>	Pinch-off Voltage V <sub>DS</sub> = 3 V, I <sub>DS</sub> = 40 mA		-2.5	-4.0	V
R <sub>TH</sub>	Thermal Resistance <sup>3</sup>		3.5	4.0	°C/W
Note: 1) T	ested with 100 Obm gate resistor 2) S C L = Single Carrier Level	2) Overal	Rth depends		t'a a

Note: 1) Tested with 100 Ohm gate resistor. 2) S.C.L. = Single Carrier Level.

3) Overall Rth depends on case mounting

## **ABSOLUTE MAXIMUM RATING<sup>1,2</sup>**

SYMBOL	CHARACTERISTIC	VALUE
V <sub>DS</sub>	Drain to Source Voltage	10 V
V <sub>GS</sub>	Gate to Source Voltage	-4.5 V
I <sub>DS</sub>	Drain Current	IDSS
I <sub>GSF</sub>	Forward Gate Current	80 mA
P <sub>IN</sub>	Input Power	@ 3dB compression
PT	Total Power Dissipation	38 W
T <sub>CH</sub>	Channel Temperature	175°C
T <sub>STG</sub>	Storage Temperature	-65/+175°C

Notes: 1.

Operating the device beyond any of the above ratings may result in permanent damage or reduction of MTTF.

2. Bias conditions must also satisfy the following equation  $P_T < (T_{CH} - T_{PKG})/R_{TH}$ , where  $\overline{T}_{PKG}$  = temperature of package, and  $P_T = (V_{DS} * I_{DS}) - (P_{OUT} - P_{IN})$ .

Specifications are subject to change without notice. Excelics Semiconductor, Inc. 310 De Guigne Drive, Sunnyvale, CA 94085 Phone: 408-737-1711 Fax: 408-737-1868 Web: <u>www.excelics.com</u>